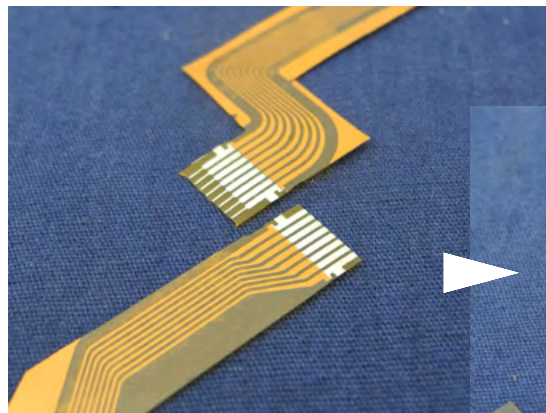
## SoundBonding Application

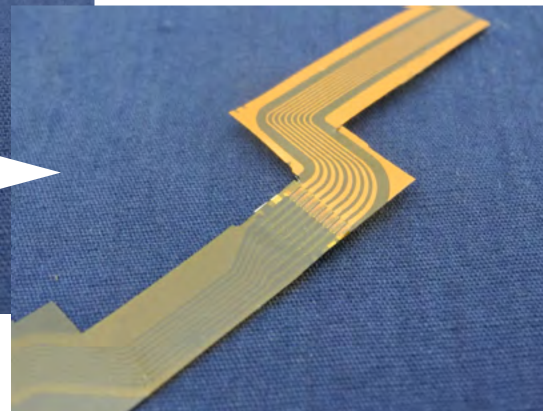
# Sound Power Clip-Ingot-Bonding

## 〈FPCのクリップ合金 音波接合〉

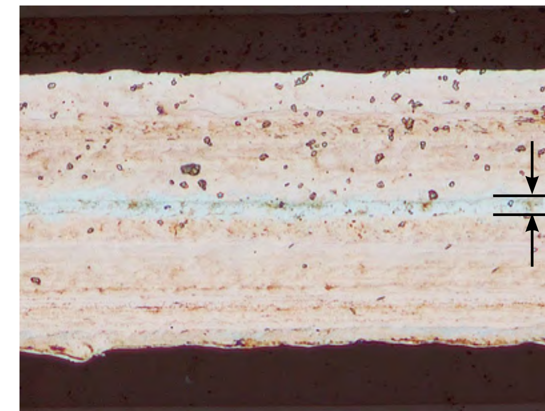


［接合前］

■銅回路 厚さ：約 50 μm
■ハンダメッキ 厚さ：10 μm

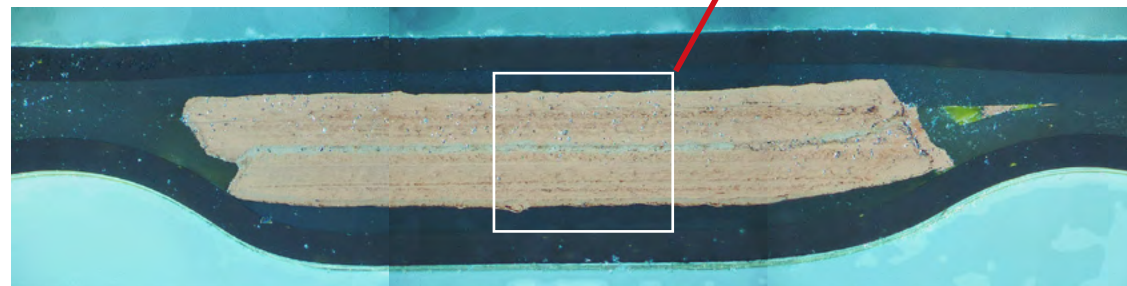


［接合後］



■ハンダメッキ接合部
厚さ：約 6.5 μm

［接合部断面拡大 x1750］



［接合部断面］

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